



LAND



SEA



AIR

THOR200-DL

2U Half Xeon D Military GPU Server



FEATURES

- Data Acquisition Military AI Xeon GPU Server
- Intel® XEON® D-1732TE Processors
- NVidia RTX A2000 (2560 CUDA)
- Extreme Temperature : -40°C to 60°C
- Options for 4x CH 3G-SDI Input
- Options for 2x CAN BUS
- MIL-STD-810 Vibration Method 514.6 : ◎Acceleration : 5.0 Grms
- MIL-STD-810 Vibration Method 514.6 : ◎PSD : 0.01257 g²/Hz
- MIL-STD-810 Shock Method 516.6 : ◎Wave Form: Half Shine Wave
- MIL-STD-810 Shock Method 516.6 : ◎Acceleration: 40G
- 2x Swappable SSD Tray
- IP65 Chassis with D389999
- Extreme Temperature : -40 ~+60 degree

Specifications

SYSTEM

Processor	Intel® XEON™ D-1732TE, 1.9/2.4 GHz, 15MB, 52W, 8C/16T
Memory type	Up to 96GB 3x DDR4 SO-DIMM
Graphic	Embedded NVIDIA® RTX™ A2000 - Ampere Architecture - 2,560 CUDA® cores, 20 RT Cores, and 80 Tensor Cores - 8GB GDDR6 memory, 128-bit
TPM	Chipset: Infineon, Type: TPM 2.0
BIOS	AMI UEFI BIOS
USB	4 x USB 3.0, 2 x USB 2.0
Ethernet	2 x 10/100/1000 Ethernet Ports (1 X LAN form mini-PCIE LAN module card)
Power Type	18V ~ 36V DC IN MIL-STD 461 EMI DC Module
Storage	2 x 2.5" SATA SSD (2x Swappable SSD Tray)
COM Port	6 x RS232/422/485 (function select by jumper)
Operating Temperature	-40°C to +60°C
Dimension	220mm(W) x 350mm(L)x88mm(H)

FRONT I/O

X1	4 x USB 2.0 with D38999 connector
X2	1 x USB 3.0 with D38999 connector
X3	2 x LAN + 2x RS232 with D38999 connector
X4	1 x VGA, 1 x DVI with D38999 connector
X5	1 x DC-in with D38999 connector

ENVIRONMENTAL

MIL-STD-810 Test	Method 500.5, Procedures I and II (Altitude, Operation): 12,192M, (40,000 ft) for the initial cabin altitude (18.8Kpa or 2.73 Psia) Method 500.5, Procedures III and IV (Altitude, Non-Operation): 15,240, (50,000 ft) for the initial cabin altitude (14.9Kpa or 2.16 Psia) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I (Temperature shock) Method 507.5, Procedure II (Temperature & Humidity) Method 509.7 Salt Spray (50±5)g/L Method 514.6, Vibration Category 24/Non-Operating (Category 20 & 24,Vibration) Method 514.6, Vibration Category 20/Operating (Category 20 & 24,Vibration) Method 516.6, Shock-Procedure V Non-Operating (Mechanical Shock) Method 516.6, Shock-Procedure I Operating (Mechanical Shock)
Reliability	No Moving Parts; Passive Cooling. Designed & Manufactured using ISO 9001 Certified Quality Program.
MIL-STD-461	CE102 basic curve, 10kHz - 30 MHz RE102-4, (1.5 MHz) -30 MHz - 5 GHz RS103, 200 MHz - 3.2 GHz, 50 V/m equal for all frequencies EN 61000-4-2: Air discharge: 8 kV, Contact discharge: 6kV EN 61000-4-3: 10V/m EN 61000-4-4: Signal and DC-Net: 1 kV EN 61000-4-5: Leads vs. ground potential 1kV, Signal und DC-Net: 0.5 kV CE and FCC
MIL-STD-1275	Steady State –20V~33V, Surge Low – 18V/500ms, Surge High – 100V/500ms Emitted spikes Injected Voltage surges Emitted voltage surges Voltage ripple (2V) Voltage spikes Starting Operation Reverse polarity
Operating Temp	-40°C to +60°C (ambient with air flow)
Storage Temp.	-40°C to +85°C
Relative Humidity	5% to 95%, non-condensing.

Ordering Information

	THOR200-X11-EHG2	THOR200-X11-TX	THOR200-X11-HML2	THOR200-DL
CPU	I7-11850HE(8C)	I7-11850HE(8C)	W-11865MLE(8C)	Xeon D-1732TE(8C)
GPU	NVIDIA RTX A2000	NVIDIA RTX A2000	NVIDIA RTX A2000	NVIDIA RTX A2000
RAM	DDR4 64GB	DDR4 64GB	DDR4 64GB	DDR4 96GB
RAID	RAID 0/1	RAID 0/1	RAID 0/1	RAID 0/1
Storage	2x2.5" SATA Drive	2x2.5" SATA Drive	2x2.5" SATA Drive	2x2.5" SATA Drive
PSU	18V~36V MIL-STD-461	18V~36V MIL-STD-461	18V~36V MIL-STD-461	18V~36V MIL-STD-461
I/O	1 x USB3.0	1 x USB3.0	1 x USB3.0	1 x USB3.0
	4 x USB2.0; 2 x RS232	4 x USB2.0; 2 x RS232	4 x USB2.0; 2 x RS232	4 x USB2.0; 2 x RS232
	2 x LAN	2 x LAN	2 x LAN	2 x LAN
	1 x DVI	HD-SDI, CANbus	1 x DVI	1 x DVI
	1 x VGA	1 x VGA	1 x VGA	1 x VGA
	1 x DC	1 x DC	1 x DC	1 x DC

Appearance



Dimension

